

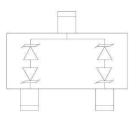
# Product data sheet

www.msksemi.com



# PESDXXXL2BT-MS HF

Semiconductor Compiance





**SOT-23** 

#### Features

- ♦ 300 Watts peak pulse power (tp = 8/20µs)
- Transient protection for high speed data lines to IEC 61000-4-2 (ESD) ±30kV (air), ±30kV(contact) IEC 61000-4-4 (EFT) 40A (5/50ns)
- ♦ Working voltages : 3.3V,5V,12V,15V,24V
- Protects two bidirectional line
- Low operating and clamping voltages
- Solid-state silicon avalanche technology

#### Applications

- Notebooks, Desktops, Servers and Video Graphics Cards
- USB Power & Data Line Protection
- Monitors and Flat Panel Displays
- ♦ I<sup>2</sup>C Bus Protection
- Portable Instrumentation
- ♦ Set Top Box

P/N	V <sub>RWM</sub> (V) (max.)	V <sub>B</sub> (V) (min.)	Ι <sub>τ</sub> (mA)	V <sub>c</sub> @1A (V) (max.)		/c V) (@A)	Ι <sub>R</sub> (μΑ) (max.)	C⊤ (pF) (max.)
PESD3V3L2BT-MS	3.3	4	1	7.0	14	18	1	100
PESD5V0L2BT-MS	5	6	1	9.8	18	13	1	75
PESD12VL2BT-MS	12	13.3	1	19	32	5	1	20
PESD15VL2BT-MS	15	16.7	1	24	38	5	1	20
PESD24VL2BT-MS	24	26.7	1	43	52	5	1	35

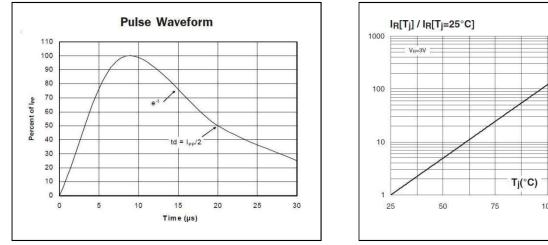
#### Electrical Characteristics@ Ta=25<sup>°</sup>Cunless otherwise

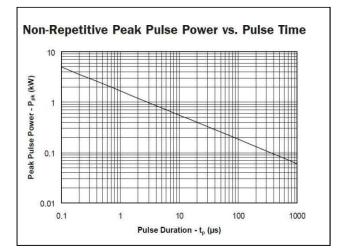
## Maximum Rating @ Ta=25 $^\circ\!\!{}^\circ\!\!{}^\circ\!\!{}^\circ\!\!{}^u$ unless otherwisespecified

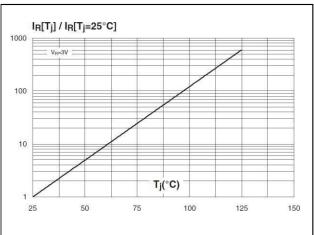
Symbol	Parameter	Ratings	Units	
Р <sub>РК</sub>	Peak Pulse Power (tp = 8/20µs)	300	Watts	
TL	Lead Soldering Temperature	260(10sec.)	°C	
TJ	Operating Temperature	-55 to +125	°C	
T <sub>STG</sub>	Storage Temperature	-55 to +150	°C	

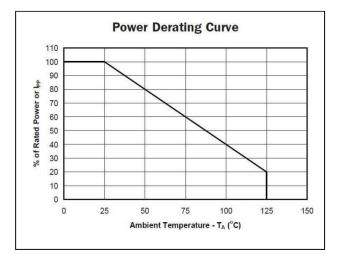


# Typical Characteristics@ Ta=25°C unless otherwise specified



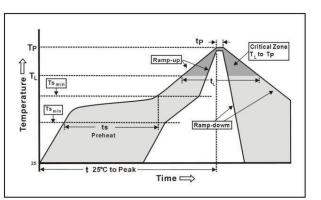






# **Soldering Parameters**

Reflow Condition		Fb – Free assembly	
	- Temperature Min (T <sub>s(Min)</sub> )	150°C	
Pre Heat	- Temperature Max (T <sub>s(Max)</sub> )	200°C	
	-Time (Min to max) (t <sub>s</sub> )	60 - 180 secs	
Average r (T <sub>L</sub> ) to pea	amp up rate (Liquidus) Temp k	3°C/second Max	
T <sub>s (Max)</sub> to T <sub>L</sub> - Ramp-up Rate		3°C/second Max	
Reflow	- Temperature (T <sub>L</sub> ) (Liquidus)	217°C	
	- Temperature (t <sub>l</sub> )	60 – 150 seconds	
Peak Tem	perature (T <sub>P</sub> )	250 <sup>+0/-5</sup> °C	
Time within 5°C of actual peak Temperature (t <sub>p</sub> )		20 – 40 seconds	
Ramp-dowm Rate		6°C/second Max	
Time 25°C to peak Temperature (T <sub>P</sub> )		8 minutes Max.	
Do not exceed		260°C	

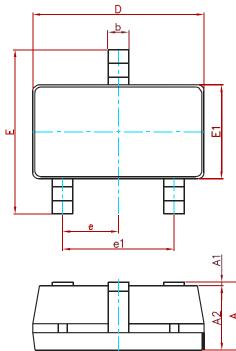


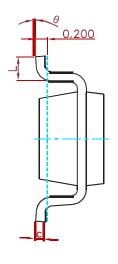


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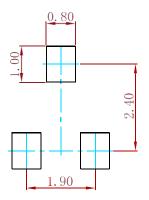
#### PACKAGE MECHANICAL DATA





Symbol	Dimensions I	n Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E1	1.500	1.700	0.059	0.067	
E	2.650	2.950	0.104	0.116	
е	0.950(BSC)		0.037(BSC)		
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
0	0°	8°	0°	8°	

#### Suggested Pad Layout



Note: 1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm

3. The pad layout is for reference purposes only.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
PESDXXXL2BT-MS	SOT-23	3000





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